



Signetics Korea

TITLE:
7.2X9.6MM 69 FBGA
2 LAYER
0.80MM PITCH
BONDING DIAGRAM

NOTE:

A9 — A1
TOP
VIEW
M9 — M1

SUB-TITLE:		CUSTOMER: UPENN	DIE PAD SIZE:	
FILE NAME: BLB-72961		DEVICE: ASDBLR	DIE SIZE (X/Y/Z): 3.6X3.6MM	
FRAME DWG#: FLB72961		CUSTOMER BD#:	BOND PAD SIZE/PITCH: 100UM / 180UM	
DETAIL DWG#: FLB72961		SIG. BD#:	WIRE DIAMETER: 1.2MIL	
FRAME STOCK#:		PART #:	LONGEST WIRE LENGTH: 30MIL	
SCALE: N/S	SHEET: 1 OF 1	FRAME CODE:	SHORTEST WIRE LENGTH: 32MIL	

DATE	REV.	DESCRIPTION	DRAWN	CHECKED	APPROVED
8/20/01	-	1ST DRAFT	MJ BAIK	DS SEO	